DEPARTMENT OF ELECTRONICS AND COMMUNICATION ENGINEERING NATIONAL INSTITUTE OF TECHNOLOGY, TIRUCHIRAPPALLI

Name of the programme and specialization M. Tech. VLSI System Course Title Low Power VLSI Systems Course Code EC668 No. of Credits 3 (Three) Course Code of Pre-requisite subject(s) EC651 Analog IC Design EC653 Basics of VLSI Image: Comparison of Credits 3 (Three) Session January 2021 Section (if, applicable) NA applicable) Name of Faculty Dr. M. Bhaskar Department ECE Email bhaskar@nitt.edu Telephone No. 0431-2503310 Name of Course Coordinator(s) (if, applicable) Nil Image: Core course Course Image: Core course Course E-mail Core course Image: Elective course Syllabus (approved in BoS) Evolution of CMOS technology, CMOS fabrication process, shallow trench isolation, Lig doped drain, Buried channel. BiCMOS and SOI CMOS technologies, second order eff Modeling of MOS devices, Threshold voltage, Body effect, Short channel and Narrow cha effects, Electron temperature, MOS capacitance. V CMOS inverters, Differential static logic circuits, Pass transistor, Bi-CMOS, SOI CMOS voltage and low power CMOS static logic circuits, Pass transistor, Bi-CMOS, SOI CMOS voltage and low power CMOS static logic circuits, Pass transistor, Bi-CMOS, SOI CMOS voltage and low power CMOS static logic circuits, Charge sharing, Noise and race problems, N Zipper, Domino, Dynamic differential, BiCMOS, low v		COURSE PLAN – P	ARTI	
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Lext Books		I extbooks, reference boo	ks Website add	resses, journals, etc
	Text Books			

- 1. J.Rabaey, "Low Power Design Essentials (Integrated Circuits and Systems)", Springer, 2009
- 2. J.B.Kuo and J.H.Lou, "Low-voltage CMOS VLSI Circuits", Wiley, 1999.

Reference Books

- 1. Michael Keating etal. "Low Power Methodology Manual For System-on-Chip Design" Springer, 2008
- 2. A.Bellaowar and M.I.Elmasry,"Low power Digital VLSI Design, Circuits and Systems", Kluwer, 1996.

COURSE OBJECTIVES

To expose the students to the low voltage device modeling, low voltage, low power VLSI CMOS circuit and system design

COUR	RSE OUTCOMES (C	0)	
	se Outcomes		Aligned Programme Outcomes (PO)
 Acquire the knowledge about various CMOS fabrication process and its modelling. Infer about the second order effects of MOS transistor characteristics. 			PO1,PO2,PO3
2. Analyze and implement various CMOS low voltage and low power static logic circuits.			PO1,PO2,PO3,PO4, PO5,PO7,PO8
	earn the design of val mamic logic circuits.	PO1,PO2,PO3,PO4, PO5,PO7,PO8	
4. Learn the different types of memory circuits and their design.			PO1,PO2,PO3,PO4, PO5,PO7,PO8
	esign and implement oplications.	PO1,PO2,PO3,PO4, PO5,PO7,PO8	
		COURSE PLAN – PART II	• •
To giv voltag VLSI o	e and low power sta computational circuit	levice fabircation and its low voltage device n tic, dynamic VLSI circuits and memory circuit s. D LEARNING ACTIVITIES	
SI. No.	Week	Торіс	Mode of Delivery
1	1 st week	Evolution of CMOS Technology,	PPT, Chalk and talk
	(3 contact hours)	CMOS fabrication process. Low voltage issues.	
2	2 nd week	STI, LDD and buried channel effects Bi-	PPT, Chalk and talk
	(3 contact hours)	CMOS fabrication, SOI-CMOS fabrication	
3	3 rd week	Second order effects of CMOS devices.	PPT, Chalk and talk
	(3 contact hours)	Short channel, narrow channel, hot carrier effects	
4	4 th week	CMOS static circuit design, Differential	PPT, Chalk and talk
	(3 contact hours)	circuit design	
5	5 th week	Bi-CMOS static circuit design, SOI CMOS	PPT, Chalk and talk
	(3 contact hours)	static circuit design	
6	6 th week	Low power, low voltage circuit techniques.	PPT, Chalk and talk
_	(3 contact hours)	Basics of dynamic logic circuit design	
7	7 th week	Disadvantages of dynamic logic circuits	PPT, Chalk and talk
0	(3 contact hours)	and solutions	DDT. Chalk and talk
8	8 th week (3 contact hours)	Dynamic differential logic circuit design	PPT, Chalk and talk
9	9 th week	Bi-CMOS dynamic logic circuit design	PPT, Chalk and talk
	(3 contact hours)		
10	10 th week	Low voltage dynamic logic circuit design	PPT, Chalk and talk
	(3 contact hours)	techniques	
11	11 th week	Memories basic concepts	PPT, Chalk and talk
	(3 contact hours)	CMOS circuits for various blocks of SRAM	
	12 th week	DRAM and SOI memory	PPT, Chalk and talk

1 2 3	Assessment - 1 (Descriptive exam) (1 st and 2 nd units)	5 th week					
2		0 10000	1 hour	20 Marks			
	(1 st and 2 nd units)						
	Assessment - 2	10 th week	1 hour	20 Marks			
3	(Descriptive exam)						
3	(3 rd unit)						
	Assessment - 3	11 th week	1 hour	20 Marks			
	(4 th unit)						
4	Assignment	12 th week	One week	10 Marks			
	(5 th unit)						
	Final Assessment	Final week	2 hours	30 Marks			
5	(Descriptive exam)						
	(All units – End semester)						
Com	pensation assessment (CPA) w	ill be conducted, if	required				
COU	RSE EXIT SURVEY (mention the	e ways in which the	e feedback abou	t the course shall			
be a	ssessed)	•					
1 F	eedback from students during clas	ss committee meetir	nas				
	edback through MIS at the end of		.90				
	RSE POLICY (preferred mode o		with students co	omnensation			
	essment policy to be specified)	i conceptinacine		Sinpensation			
	RSE ASSESSMENT:						
	Attending all the assessments are	MANDATORY for e	werv student				
	f any of the student is not able to a			ent descriptive			
	examination due to genuine reasor						
				aoparanoneor			
	medical grounds only), student is permitted to attend CPA. Submission of assignments is MANDATORY for every student within the stipulated time						
	failing which 10% weightage will not be considered for final grade assessment						
	There will not be any improvement						
	assessment test.						
5 F	Finally, every student is expected t	o score minimum m	arks as per the re	aulations of the			
	nstitute out of the total assessmen						
	tudent will be declared fail and 'F'		-				
	only FORMATIVE ASSESSMENT.	-					
	DE OF CORRESPONDENCE (em						
	All students are advised to check to		egularly. All the de	etails about the			
S	chedule of classes, schedule of a	ssessments, course	material and any	other information			
n	egarding the course will be sent through webmail only.						
2 E	oubts regarding the course can be clarified by fixing proper timing with the teacher during						
	orking hours only.						
	Queries, if any regarding the cours	e shall only through	email to the teach	her.			
	IPENSATION ASSESSMENT PO						
1 A	Any student who fails to maintain 7	75% attendance only	on reasonable m	nedical/official			
g	rounds needs to appear for the co	ompensation assess	ment (CPA) class	es.			
2 7	The portion for compensation asse	<u>ssment will be th</u> e p	ortion of assessm	nent 1 and 2.			
	ENDANCE POLICY (A uniform at	• •	specified below sh	all be followed)			
1. A	At least 75% attendance in each co	ourse is mandatory.					
2. A	A maximum of 10% shall be allowed under On Duty (OD) category.						
	Students with less than 65% of attendance shall be prevented from writing the f						
	issessment and shall be awarded						

ACADEMIC DISHONESTY & PLAGIARISM

- 1. Possessing a mobile phone, carrying bits of paper, talking to other students, copying from others during an assessment will be treated as punishable dishonesty.
- 2. Zero mark to be awarded for the offenders. For copying from another student, both students get the same penalty of zero mark.
- 3. The departmental disciplinary committee including the course faculty member, PAC chairperson and the HoD, as members shall verify the facts of the malpractice and award the punishment if the student is found guilty. The report shall be submitted to the Academic office.

The above policy against academic dishonesty shall be applicable for all the programmes. ADDITIONAL INFORMATION

The faculty is available for consultation at times as per the intimation given by the faculty. **FOR APPROVAL**

M. 181

21-01-2021 Course Faculty _

HOD

CC-Chairperson _